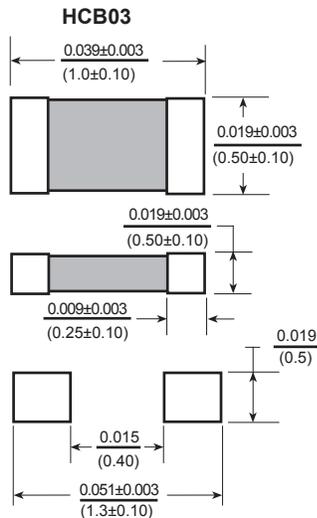


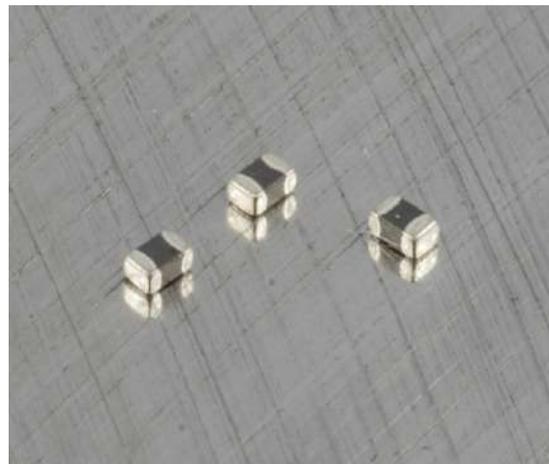


High Current Beads

HCB03



Dimensions: $\frac{\text{Inches}}{\text{(mm)}}$



Features

- 0402 Surface mount EMI suppression components
- Nickel barrier termination for excellent resistance to solder heat
- High current capacity
- Wide range of impedance values
- Multi layer technology
- Low DCR
- Flow and reflow soldering

Electrical

Impedance Range: HCB03 10Ω to 1000Ω

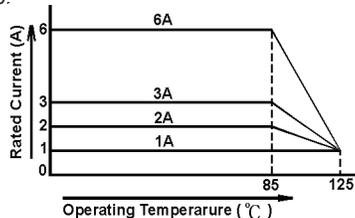
Tolerance: 25% over entire range

Operating Temp: -55°C ~ +125°C

Storage Temp: Under 25°C at 40~60% Humidity

Rate Current: Based on temp rise not to exceed 30°C

Rate current is derated as indicated below based on operating temp.



Resistance to Solder Heat

Pre-Heat 150°C, 1 minute

Solder Composition: Sn/Ag3.0/Cu0.5

Solder Temp: 260±5°C for 10sec ±1 sec.

Minimum of 75% of Electrode covered with new solder.

Impedance within 30% of initial value.

Allied Part Number	Impedance (Ω) @ 100MHz ±25%	DCR (Ω Max)	Rated Current (mA)
HCB03-100-RC	10	0.03	2000
HCB03-250-RC	25	0.05	1700
HCB03-300-RC	30	0.05	1700
HCB03-320-RC	32	0.05	1700
HCB03-400-RC	40	0.075	150
HCB03-500-RC	50	0.075	1500
HCB03-600-RC	60	0.075	1500
HCB03-680-RC	68	0.09	1200
HCB03-700-RC	70	0.09	1200
HCB03-800-RC	80	0.09	1200
HCB03-101-RC	100	0.09	1200
HCB03-121-RC	120	0.09	1400
HCB03-151-RC	150	0.14	1400
HCB03-181-RC	180	0.14	900
HCB03-221-RC	220	0.18	1100
HCB03-601-RC	600	0.34	700
HCB03-102-RC	1000	0.49	500

All specifications subject to change without notice.

Test Equipment

(Z): HP4291A RF Impedance/Material Analyzer

(RDC): Chen Hwa 502BC

Physical

Packaging: 10000pcs per 7 inch reel.

Marking: None